

AF/JPW



Atty. Docket No.: 2946-D-Z

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Jane Lu et al

Group Art Unit 2841

Serial No. 10/784,813

Examiner Jeremy C. Norris

Filed: February 24, 2004

For: METAL CORE SUBSTRATE PRINTED BOARD ENABLING
THERMALLY ENHANCED BALL GRID ARRAY (BGA)
PACKAGES AND METHOD

RESPONSE TO FINAL REJECTION

Mail Box AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Office Action (final) mailed April 19, 2005.

REMARKS/ARGUMENTS

The claims have not been amended.

Claims 11 - 17 are pending in the application.

Applicants respectfully request reconsideration of the rejection of claims 11, 12, 15 and 16 under 35 U.S.C. §102(e) as being anticipated by Terui (US 6,538,319).

Initially, it will be observed that in the Background of the Invention Terui states:

This invention relates to a semiconductor device, and particularly to a structure of a small-sized area